



PATENT APPLICATION
Docket No. 9903-078
Client No. S02US013D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Young-Hee SONG, et al.

Serial No. 10/651,813 Examiner: Williams, Alexander O

Filed: August 28, 2003 Art Unit: 2826

Confirmation. No. 9556

For: SEMICONDUCTOR CHIP HAVING BOND PADS AND
MULTI-CHIP PACKAGE

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Responsive to the Office Action, dated June 28, 2004, please amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 11 of this paper.

11/03/2004 AWONDAF1 00000163 10651813

01 FC:1202 72.00 OP
02 FC:1251 110.00 OP

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Amendment; Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450
Date: October 26, 2004


Li Mei Vermilya